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(71) Applicant *(for all designated States except US)*: **SCHOTT AG** [DE/DE]; Hattenbergstr. 10, 55122 Mainz (DE).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **LEIB, Jürgen** [DE/DE]; Philipp-Dirr-Strasse 44, 85354 Freisingen (DE).

(74) Agent: **HERDEN, Andreas**; Blumbach, Zinngrebe, Alexandrastrasse 5, 65187 Wiesbaden (DE).

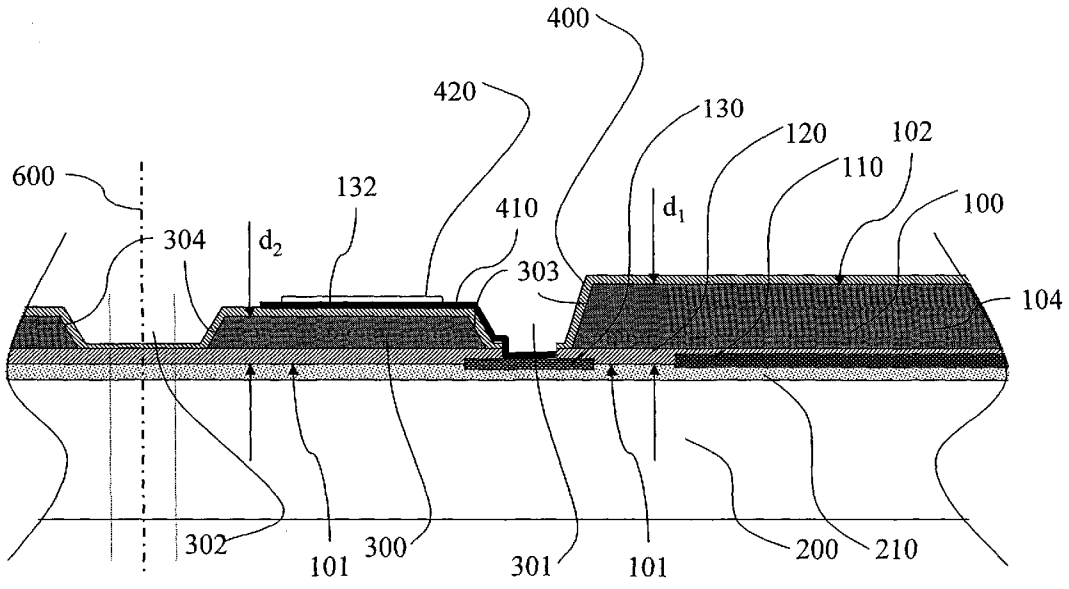
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(54) **Title:** PROCESS FOR PACKAGING COMPONENTS, AND PACKAGED COMPONENTS



(57) **Abstract:** The invention relates to a wafer level packaging process and to a component packaged in this way. It is an object of the invention to provide a process of this type which ensures a high yield, is also suitable for optical and/or micromechanical components and achieves improved thermo-mechanical decoupling of the connections from the functional regions. According to the process of the invention, the base substrate is divided into body regions and connection regions, the body regions in each case extending over the functional regions and the connection regions being offset with respect to the contact-connection recesses. The component is then thinned in the body regions or the connection regions until it has different thicknesses in the body regions and the connection regions, before the wafer assembly is diced into chips.

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